

Film Chip Capacitor

Type : **ECPU**

Stacked dielectric and inner electrode with simple mold - less construction

■ Features

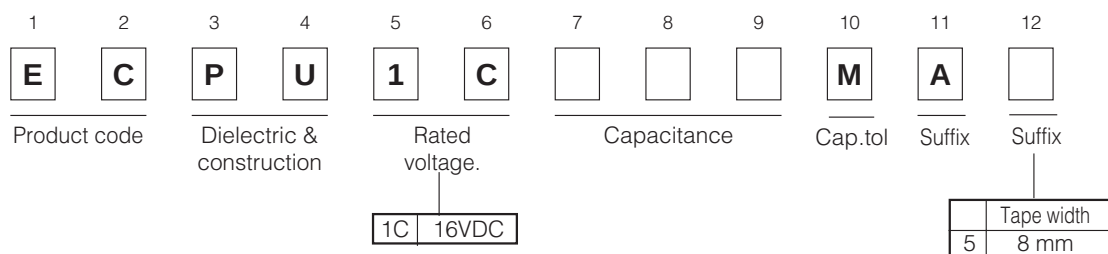
- Low ESR
- Max. capacitance values 1.0μF
- Smallest package size in film capacitors 3225/1μF
- Applicable for reflow soldering



■ Recommended Applications

- Noise suppressor
- Coupling

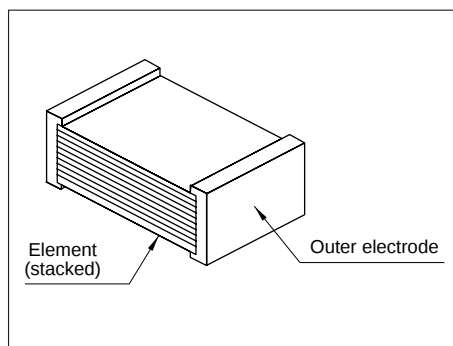
■ Explanation of Part Numbers



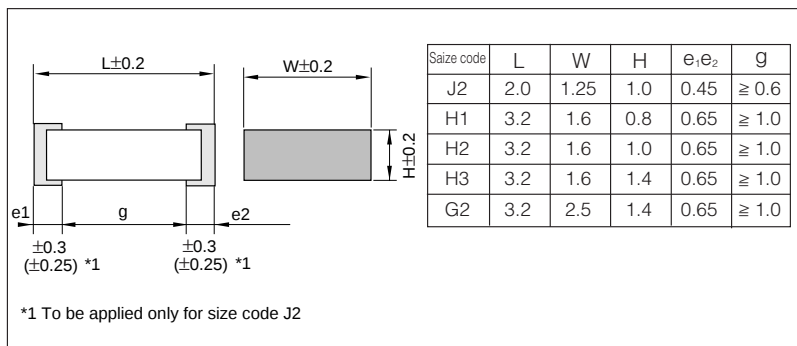
■ Specifications

Category temp. range	- 40 to + 85°C
Rated voltage	16VDC
Capacitance range	0.1 to 1.0μF (E6)
Capacitance tolerance	± 20% (M)
Dissipation factor	1.5%max. (20°C, 1kHz)
CWithstand voltage	Between terminals: Rated volt (VDC)x175% 1 to 5s
Insulation resistance	C≤0.33μF:1000MΩ min.(20°C, 10VDC 60s) C>0.33μF:300MΩ • μFmin.(20°C, 10VDC 60s)
Soldering conditions	Reflow :soldering240°Cmax. and 30sec max.at more than 210°C (Temp.at cap.surface)

■ Construction



■ Dimensions in mm (not to scale)



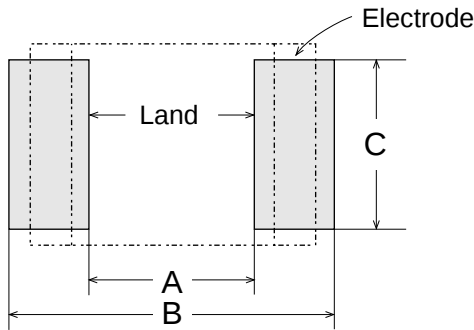
■Taping Specification for Automatic Insertion(Mounting)

Refer to the PDF file of the taping specification.

■Rating, Dimensions & Quantity/Reel

Part No.	Cap. (μ F).	Dimensions (mm)				Quantity
		L	W	H	Size Code	
ECPU1C104MA5	0.1	2.0	1.25	1.0	J2	3000
ECPU1C154MA5	0.15	3.2	1.6	0.8	H1	
ECPU1C224MA5	0.22	3.2	1.6	0.8	H1	
ECPU1C334MA5	0.33	3.2	1.6	1.0	H2	
ECPU1C474MA5	0.47	3.2	1.6	1.4	H3	2000
ECPU1C684MA5	0.68	3.2	1.6	1.4	H3	
ECPU1C105MA5	1.0	3.2	2.5	1.4	G2	

■Example for Land Dimensions(mm)



Size Code	Land dimensions Reflow soldering		
	A	B	C
J2	0.8	2.4	1.1
H1	1.8	3.6	1.4
H2	1.8	3.6	1.4
H3	1.8	3.6	1.4
G2	1.8	3.6	2.3